

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S) Fu, C. et al.

GROUP ART UNIT: 3723

APPLN. NO.: 09/712,749

EXAMINER: NGUYEN, David T.

FILED: 11/14/2000

RESPONSE UNDER 37 CFR 1.116

EXPEDITED PROCEDURE

TITLE: LOW PROFILE INTEGRATED MODULE INTERCONNECTS AND  
METHOD OF FABRICATION

Certificate of Transmission under 37 CFR 1.8

I hereby certify that this correspondence is being  
facsimile transmitted to the Patent and Trademark Office

on February 12, 2003

Signature

Samuel Hartway  
Printed Name of Person Signing Certificate

RESPONSE UNDER 37 CFR 1.116

Honorable Assistant Commissioner of Patents,  
Washington, D.C. 20231

SIR:

In response to the Office Action mailed JANUARY 17, 2003, please amend  
and reconsider the above-identified application as shown below in the included  
pages entitled "Amended Claims" and "Remarks."